KIRU KEZURU MIGAKU

DISCO HI-TEC EUROPE

Semi Automatic Wafer Mounter

SAM-C8/12P

Semic automatic wafer mounter with small footprint for easy and flexible mounting on dicing frames

Support for semiconductor manufacturing lines to ensure a controlled and repeatable wafer mounting process

Support for workpieces with 6’’, 8’’, and 12’’ wafers, all substrates, round or square shapes for mounting on pre-cut tape

Highly flexible in operating range due to exchange of various chuck tables and frame tables (option)

ESD and UV cover for multiple applications

Die Attach Film (DAF) heating function (option)

Environmental-conscious design and high UPH at the same time

The SAM-C8/12P is our state-of-the-art mounter with intuitive control and fast booting due to the graphical user interface

High and stable output

The SAM-C8/12P offers fast processing time appr. 15 seconds per wafer

A stable and reapeatable mounting process

Ultra fast booting appr. 10 seconds

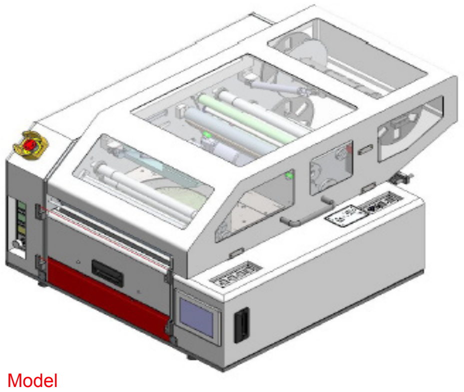
Easy and fast to operate

Low error rate and fast handling through smart operation system

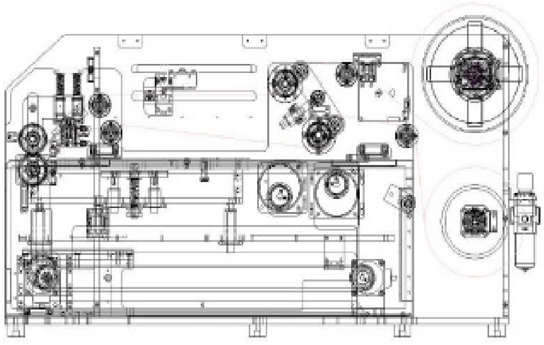
Graphical User Interface with touch display as the main control panel

Additional Fast-Operation-Buttons

Controlled tape tension via software



Model



Layout

The SAM-C8/12P is designed for easy and flexible customization and fast adjustment

Adjustable pinch roller pressure for easy handling of any kind of dicing tape (thickness) via air cylinder

Any chuck table option can be realised

Specifications

Specification	Unit	
Wafer Diameter	mm	all up to 300 or even larger
Wafer attachment precision and X/Y direction (frame mount	mm	±0.5 or less
Wafer attachment precision and θ direction (frame mount)	deg	±0.5 or less
Dicing tape attachment precision and X/Y direction	mm	±1.0 or less
Machine dimensions (W×D×H)	mm	950 × 800 × 540
Machine weight	kg	appr. 200

Environmental conditions

- Use clean, oil-free air at a dew point of -15 ℃ or less. (Use a residual oil: 0.1 ppm. Filtration rating: 0.01 µm/99.5 % or more).
- Keep room temperature fluctuations within ±1 ℃ of the set value. (Set value should be between 20 - 25 ℃).
- The machines should be used in an environment, free from external vibration. Do not install machine near a ventilation opening, heat generation equipment or oil mist generating parts.

* All pressures specified above are gauge pressures.

* As the above specification may change due to technical modifications. Please confirm when placing your order.

* For further information, please contact your local sales representative.

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